

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Kangho Lee</td> <td>02/19/2013</td> </tr> <tr> <td>Wei-Chuan Chen</td> <td>02/18/2013</td> </tr> <tr> <td>Seung H. Kang</td> <td>02/19/2013</td> </tr> </tbody> </table>		Name	Execution Date	Kangho Lee	02/19/2013	Wei-Chuan Chen	02/18/2013	Seung H. Kang	02/19/2013
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Kangho Lee	02/19/2013								
Wei-Chuan Chen	02/18/2013								
Seung H. Kang	02/19/2013								
RECEIVING PARTY DATA									
Name:	QUALCOMM Incorporated								
Street Address:	5775 Morehouse Drive								
Internal Address:	Patent Department								
City:	San Diego								
State/Country:	CALIFORNIA								
Postal Code:	92121-1714								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13770526</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13770526				
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Application Number:	13770526								
CORRESPONDENCE DATA									
Fax Number:	8586582502								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	858-658-5787								
Email:	Patent.Docketing.US@qualcomm.com								
Correspondent Name:	QUALCOMM Incorporated								
Address Line 1:	5775 Morehouse Drive								
Address Line 2:	Patent Department								
Address Line 4:	San Diego, CALIFORNIA 92121-1714								
ATTORNEY DOCKET NUMBER:	122782								
NAME OF SUBMITTER:	Sam Talpalatsky								
Total Attachments: 4 source=122782_EFAR-REC-as-filed-02-27-13#page1.tif source=122782_EFAR-REC-as-filed-02-27-13#page2.tif source=122782_EFAR-REC-as-filed-02-27-13#page3.tif source=122782_EFAR-REC-as-filed-02-27-13#page4.tif									

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ASSIGNMENT

WHEREAS, WE,

1. Kangho Lee, a citizen of the South Korea, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California
2. Wei-Cbuan Chen, a citizen of Taiwan, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of Taipei, Taiwan
3. Seung H. Kang, a citizen of the United States, having a mailing address of 5775 Morehouse Drive, San Diego, CA 92121; and a resident of San Diego, California

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **AMORPHOUS ALLOY SPACER FOR PERPENDICULAR MTJs** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/770,526 filed February 19, 2013, Qualcomm Reference No. 122782, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/676,487, filed July 27, 2012, Qualcomm Reference No. 122782P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

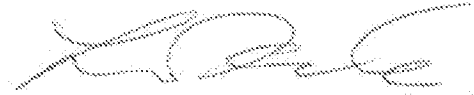
its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 02/19/2013 
LOCATION DATE Kangho Lee

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Taipei, Taiwan, on 2/18/2013 Wei-Chuan Chen
LOCATION DATE Wei-Chuan Chen

Done at _____, on _____
LOCATION DATE Seung H. Kang

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Wei-Chuan Chen

Done at San Diego CA, on 2/19/2013
LOCATION DATE

Seung H. Kang